

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0738002000

Status:

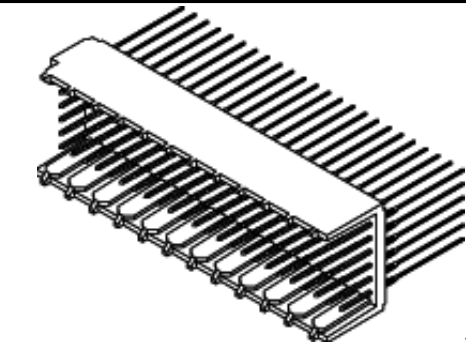
Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Midplane Header, Vertical, SMC, Press-Fit, Long Pin, Open End Option, 72 Circuits



Series
image - Reference only

Documents:

[Drawing \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)

[Product Specification PS-73780-999 \(PDF\)](#)

General

Product Family	Backplane Connectors
Series	73800
Application	Midplane
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.453 In
PC Tail Length (mm)	11.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.156 In
PCB Thickness Recommended (mm)	3.95 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	35.2
Plating min: Termination (µm)	0.88
Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C

Electrical

Current - Maximum per Contact	1A
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EU RoHS

China RoHS

Compliance Status

Not Reviewed

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73800Series](#)

Mates With
[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.
Global

Description	Product #
Flat Rock Tooling for	0622013700
Pneumatic Press	

Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0868
Product Specification	PS-73780-999
Sales Drawing	SD-73800-001

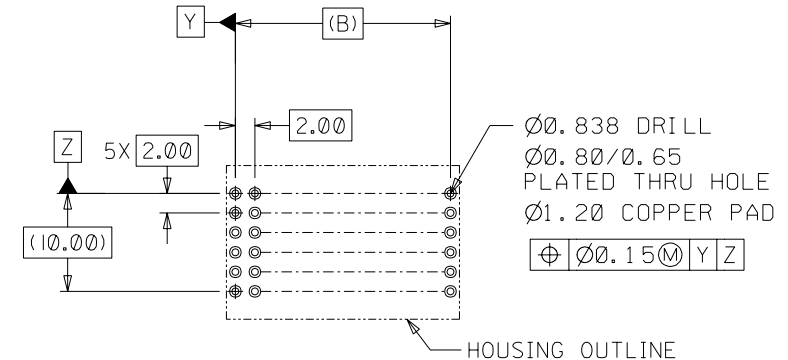
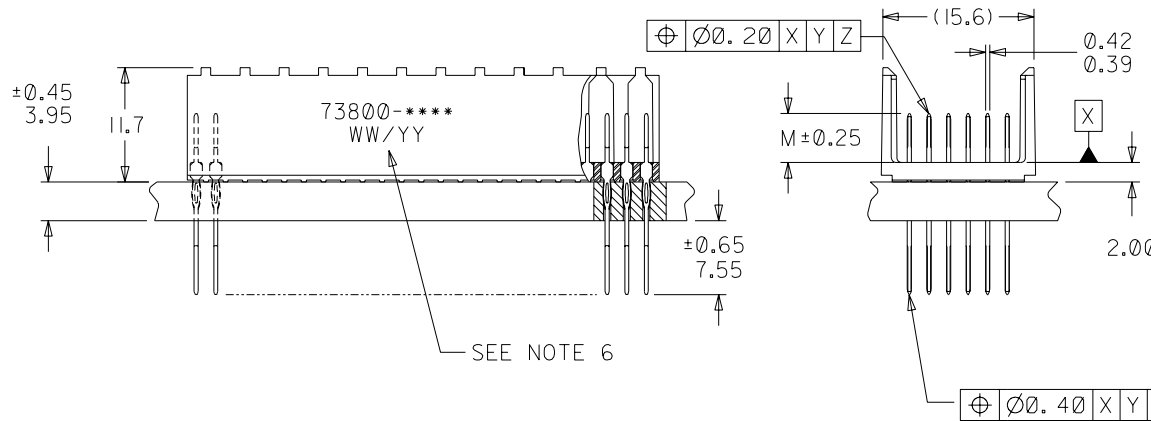
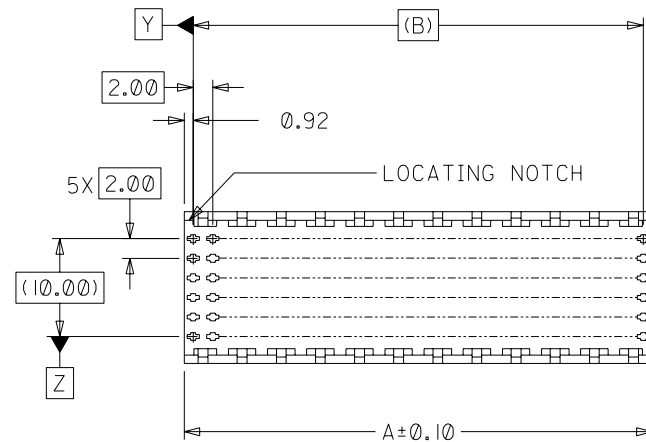
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This document was generated on 05/14/2010

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NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; SELECTIVE TIN/LEAD (Sn/Pb) IN COMPLIANT AREA, NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. PACKAGE PER PK-70873-0868.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 3.95±0.45

MATERIAL NUMBER	NUMBER OF CONTACTS	DIM "A"	DIM "B"	DIM "M"	PLATING
73800-0000	72	23.84	22.00	5.00	GOLD/GOLD FLASH
73800-0200	72	23.84	22.00	6.00	GOLD/GOLD FLASH
73800-1000	144	47.84	46.00	5.00	GOLD/GOLD FLASH
73800-1200	144	47.84	46.00	6.00	GOLD/GOLD FLASH
73800-2000	72	23.84	22.00	5.00	GOLD/TIN-LEAD
73800-2200	72	23.84	22.00	6.00	GOLD/TIN-LEAD
73800-3000	144	47.84	46.00	5.00	GOLD/TIN-LEAD
73800-3200	144	47.84	46.00	6.00	GOLD/TIN-LEAD

REVISED
EC NO: UCP2004-1438
DRWN: BINGHAM 04/02/04
CHK: REED 04/02/04
APPR: BIXLER 04/02/04
H

DESCRIPTION
MAJOR
CRITICAL
REV

GENERAL TOLERANCES:
(UNLESS SPECIFIED)
4 PLACES ±0.1
3 PLACES ±0.1
2 PLACES ±0.05
1 PLACE ±0.1
ANGULAR: ± 1/2°
DRAFT WHERE APPLICABLE MUST
REMAIN WITHIN DIMENSIONS

SCALE
2 : 1
DESIGN UNITS
mm INCH
DRAWN BY & DATE
JBINGHAM 97/05/16
CHECKED BY & DATE
SREED 97/05/16
APPROVED BY & DATE
CBIXLER 97/05/16
CAD FILENAME
S73800X1.DGN

TITLE:
SALES ASSEMBLY
HDM DOUBLE-END MIDPLANE
OPEN END OPTION
MOLEX INCORPORATED
MATERIAL NO.
DRAWING NO.
SD-73800-001
SHEET NO.
1 OF 1
SIZE
B

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9